FORM PTO-1449	SERIAL NO.	CASE NO.	
·	To Be Assigned	2003P11250US	
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE	FILING DATE	GROUP ART UNIT	
STATEMENT	Herewith	To. Be Assigned	
(use several sheets if necessary)	APPLICANT(S): John A. Hossad	(S): John A. Hossack et al.	

REFEREN	CE DESIG	NATION U.S	PATENT DO	CUMENTS		
EXAMINE INITIAL		DOCUMENT NUMBER Number-Kind Code (If known)	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
1.0	A1	4,413,520	11/08/1983	Murakami et al.		
$-\overline{L}$	A2	4,801,835	01/31/1989	Nakaya et al.		
	A3	4,960,320	10/02/1990	Taniura		
	A4	4,984,465	01/15/1991	Piel, Jr. et al.		
	A5	5,105,666	04/21/1992	Steinacher		
	A6	5,160,870	11/03/1992	Carson et al.	 	7
	. A7	5,167,231	12/01/1992	Matsui		
	A8	5,175,709	12/29/1992	Slayton et al.		
	A9	5,241,209	08/31/1993	Sasaki	7	
	A10	5,296,777	03/22/1994	Mine et al.		
	A11	5,406,163	04/11/1995	Carson et al.	<u> </u>	
	A12	5,962,790	10/05/1999	Lynnworth et al.	7	
11.	A13	6 359 375	03/19/2002	Guo et al.	7	. /

EXAMINER INITIAL	(Ir sym	OTHER ART — NON PATENT LITERATURE DOCUMENTS aclude name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, posium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.
a.s.	A14	"3D Simulation of Controlled Micromachined Capacitive Ultrasound Transducers," by M. Kaltenbacher, H. Landes, K. Neiderer, and R. Lerch at the University of Erlangen, Germany; 1999 IEEE Ultrasonics Symposium; pgs. 1155-1158.
1	A15	"A New Vibration Mode in Tall, Narrow Piezoelectric Elements," by John D. Larson at H-P Laboratories, Hewlett-Packard Company; 1979 IEEE Ultrasonics Symposium; pgs. 108-113.
	A16	"Investigation of Cross-Coupling in 1-3 Piezocomposite Arrays," by D. Certon, N. Felix, Student Member, IEEE, E. Lacase, F. Teston, and F. Patat; IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control, Vol. 48, No. 1; dated January 2001; pgs. 85-92.
	A17	"Radiation Pattern Distortion Caused by the Interelement Coupling in Linear Array Transducers," by N. Lamberti; 1999 IEEE Ultrasonics Symposium; pgs. 1071-1075.
	A18	"Non-Ideal Radiators in Phased Array Transducers," by J. D. Larson at Hewlett-Packard Laboratories; 1981 Ultrasonics Symposium; pgs. 673-684.
	A19	"Crosstalk Reduction With a Micromachined Diaphragm Structure for Integrated Ultrasound Transducer Arrays," by J.H. Mo, Student Member, IEEE, J. Brian Fowlkes, A. L. Roginson, Member, IEEE, and P. L. Carson; 1992 IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control, Vol. 39, No. 1; dated January 1992; pgs. 48-53.
AI.	A20	"Cross-Talk Paths in Array Transducers," by J.F. Guess, C.G. Oakley, S.J. Douglas and R.D. Morgan; 1995 IEEE Ultrasonics Symposium; pgs. 1279-1282.

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DATE CONSIDERED

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EXAMINER	n.	OTHER ART – NON PATENT LITERATURE DOCUMENTS (Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial,		
INITIAL (Include name of symposium, catalo		posium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.		
S.D.	A21	"Crosscoupling Analysis for Wideband Arrays," by R. Johnson; 1995 IEEE Ultrasonics		
10.0		Symposium; pgs. 1349-1352.		
	A22	"Time-Domain Modeling of Composite Arrays for Underwater Imaging," by G. L. Wojcik, D.K. Vaughan, V. Murray, and J. Mould Jr.; 1994 Ultrasonics Symposium; pgs. 1027-1032.		
	A23	"Evaluation of Laser Probe Performances for Measuring Cross-Coupling in 1-3 Piezocomposite		
		Arrays," by D. Certon, N. Felix, L. Pascal, T.H. Hue, F. Patat, and M. Lethiecq; 1999 IEEE Ultrasonics Symposium; pgs. 1091-1094.		
	A24	"Theory for Cross-Coupling," by G.S. Kino and R. Bear; 1983 Ultrasonics Symposium; pgs. 1013-1019.		
	A25	"Radiation from Finite Phased and Focused Linear Array Including Interaction," by J. Assaad and C. Bruneel; 1997 Acoustical Society of America; Received May 1, 1996 and accepted October 27, 1996; pgs. 1859-1867.		
	A26	"3D Simulation of Controlled Micromachined Capacitive Ultrasound Transducers," by M. Kaltenbacher, H. Landes, K. Nieder, and R. Lerch; 1999 IEEE Ultrasonics Symposium; pgs 1155-1158.		
	A27	"Time-Domain Models of MUT Array Cross-Talk in Silicon Substrates," by G. Wojcik, J. Mould, and P. Reynolds A. Fitzgerald, P. Wagner, and Igal Ladabaum; 2000 IEEE Ultrasonics Symposium.		
	A28	"Experimental Investigation of Cross-Coupling and its Influence on the Elementary Radiation Pattern in 1D Ultrasound Arrays," by N. Felix, D. Ceron, E. Lacaze, M. Lethiecq, and F. Patat; 1999 IEEE Ultrasonics Symposium; pgs. 1053-1056.		
	A29	"An Experimental Investigation of the Cross-Coupling Between Elements of an Acoustic Imaging Array Transducer," by J. Fleming Dias; 1982 by Academic Press, Inc.; Ultrasonic Imaging Vol. 4, pgs. 44-55 (1982)3		
	A30	"Silicon Substrate Ringing in Microfabricated Ultrasonic Transducers," by Igal Ladabaum P. Wagner, C. Zanelli, J Mould, P. Reynolds, and G. Wojcik; 2000 IEEE Ultrasonics Symposium.		
A.J.	A31	"Prediction and Measurement of Cross-Talk Effects in a Periodic Linear Array Built Using Ultrasound Micormachining," by S. Ballandras, P.F. Edona, F. Langrognet, W. Steichem, and G. Perre; 2000 IEEE Ultrasonics Symposium.		

EXAMINER	The DATE CONSIDERED	3/6/5

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